

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

HIGH-PRESSURE PROCESSING CHAMBER FOR A
SEMICONDUCTOR WAFER

Application Number: 10/680783



Confirmation Number: 5859

First Named Applicant: William Jones

Attorney Docket Number:

Search string: (5882165 or 5888050 or 5898727 or 5900107
or 5904737 or 5928389 or 5932100 or 5934856
or 5934991 or 5979306 or 5980648 or 5981399
or 5989342 or 6005226 or 6017820 or 6029371
or 6035871 or 6037277 or 6053348 or 6056008
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or 6159295 or 6164297 or 6186722 or 6203582
or 6216364 or 6228563 or 6235634 or 6239038
or 6241825 or 6251250 or 6244121 or 6277753
or 6286231 or 6305677 or 6334266 or 6344174
or 6388317 or 6389677 or 6418956 or 6436824
or 6454945 or 6464790),pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
<input checked="" type="checkbox"/>	1	5882165	1999-03-16	Maydan et al.			
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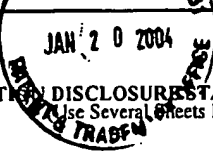
Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal. The current electronic filing contains part 3 out of a total of 4 electronic filings.

Signature

Examiner Name	Date
<i>[Signature]</i>	9/23/05

FORM PTO-1449 (Modified)				U.S. Department of Commerce Patent and Trademark Office		Attorney Docket No.: SSI-04001		Serial No.: 10/680,783	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets if Necessary)						Applicant: William Dale Jones			
(37 CFR § 1.98(b))						Filing Date: October 6, 2003		Group Art Unit: 1765	
FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS									
		Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation		
							Yes	No	
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Examiner: <i>HL</i>						Date Considered: 9/23/05			
EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.									

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(37 CFR § 1.98(b))				Filing Date: October 6, 2003		Group Art Unit: 1765	

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		Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation	
							Yes	No
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Examiner: <u>AK</u>	Date Considered: <u>9/23/05</u>
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EXAMINER:	Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.
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1/12/04

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR
WAFER

Application Number: 10/680783

10/680783

Confirmation Number: 5859

First Named Applicant: William Jones

Attorney Docket Number:

Search string: (6521466 or 6541278 or 6546946 or 6550484 or 6558475 or
6561213 or 6561220 or 6561481 or 6561767 or 6564826 or
5217043 or 20020001929).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	6541278	2003-04-01	Morka et al.	B1		
	3	6546946	2003-04-15	Dunmire	B1		
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Note: Applicant is not required to submit a paper copy of cited US Published Applications

Init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020001929	2002-01-03	Biberger et al.	A1		

Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal.
The current electronic filing contains part 4 out of a total of 4 electronic filings.

Signature

Examiner Name	Date
<i>[Signature]</i>	9/23/05

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8
Stylesheet Version v1.8.0

JAN 20 2004

Title of Invention: HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER

Application Number: 10/680783 ***10/680783***

Confirmation Number: 5859

First Named Applicant: William Jones

Attorney Docket Number:

Search string: (2617719 or 2625886 or 3744660 or 3968885 or 4029517 or 4091643 or 4245154 or 4341592 or 4355937 or 4367140 or 4406596 or 4422651 or 4474199 or 4522788 or 4549467 or 4592306 or 4601181 or 4626509 or 4670126 or 4682937 or 4693777 or 4749440 or 4778356 or 4788043 or 4789077 or 4823976 or 4825808 or 4827867 or 4838476 or 4865061 or 4879431 or 4917556 or 4924892 or 4951601 or 4960140 or 4983223 or 5011542 or 5044871 or 5062770 or 5071485 or 5105556 or 5143103 or 5167716 or 5169296 or 5169408 or 5185296 or 5186718 or 5188515 or 5190373 or 5191993),pn.

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Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Remarks

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The current electronic filing contains part 1 out of a total of 4 electronic filings.

Signature

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Ken KU	9/23/05

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1/12/2004

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Application Number: 10/680783

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Confirmation Number: 5859

First Named Applicant: William Jones

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Search string: (5193560 or 5195878 or 5213485 or 5221019 or 5222876 or 5224504 or 5236669 or 5237824 or 5240390 or 5243821 or 5246500 or 5251776 or 5267455 or 5280693 or 5285352 or 5288333 or 5313965 or 5314574 or 5328722 or 5337446 or 5339844 or 5355901 or 5368171 or 5370741 or 5377705 or 5401322 or 5404894 or 5412958 or 5417768 or 5433334 or 5447294 or 5503176 or 5505219 or 5509431 or 5526834 or 5533518 or 5571330 or 5589224 or 5621982 or 5629918 or 5644855 or 5649809 or 5656097 or 5669251 or 5702228 or 5706319 or 5746008 or 5797719 or 5798126 or 5881577).pn.

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	3	5213485	1993-05-25	Widen			
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Remarks

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41	6286231	2001-09-11	Bergman et al.	B1
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48	6436824	2002-08-20	Chopel et al.	B1
49	6454945	2002-09-24	Weigl et al.	B1
50	6464790	2002-10-15	Sherstinsky et al.	B1

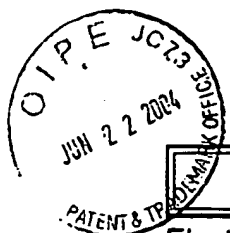
Remarks

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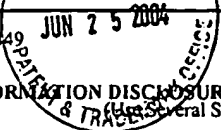
Examiner Name	Date



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE CHAMBER FOR A SEMICONDUCTOR WAFER																																																																																																
<div>Application Number: 10/680783</div> <div>Confirmation Number: 5859</div> <div>First Named Applicant: William Jones</div> <div>Attorney Docket Number:</div> <div>Search string: (5186594 or 5769588 or 5906866 or 5975492 or 6122566 or 6355072 or 6454519 or 20030205510 or 20040020518).pn.</div> <div><div>US Patent Documents</div><div>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</div><table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td><input checked="" type="checkbox"/></td><td>1</td><td>5186594</td><td>1993-02-16</td><td>Toshima et al.</td><td></td><td></td><td></td></tr><tr><td><input type="checkbox"/></td><td>2</td><td>5769588</td><td>1998-06-23</td><td>Toshima et al.</td><td></td><td></td><td></td></tr><tr><td><input type="checkbox"/></td><td>3</td><td>5906866</td><td>1999-05-25</td><td>Webb</td><td></td><td></td><td></td></tr><tr><td><input type="checkbox"/></td><td>4</td><td>5975492</td><td>1999-11-02</td><td>Brenes</td><td></td><td></td><td></td></tr><tr><td><input type="checkbox"/></td><td>5</td><td>6122566</td><td>2000-09-19</td><td>Nguyen et al.</td><td></td><td></td><td></td></tr><tr><td><input type="checkbox"/></td><td>6</td><td>6355072</td><td>2002-03-12</td><td>Racette et al.</td><td>B1</td><td></td><td></td></tr><tr><td><input checked="" type="checkbox"/></td><td>7</td><td>6454519</td><td>2002-09-24</td><td>Toshima et al.</td><td>B1</td><td></td><td></td></tr></tbody></table><div><div>US Published Applications</div><div>Note: Applicant is not required to submit a paper copy of cited US Published Applications</div><table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Pub. No.</th><th>Date</th><th>Applicant</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td><input checked="" type="checkbox"/></td><td>1</td><td>20030205510</td><td>2003-11-06</td><td>Jackson</td><td>A1</td><td></td><td></td></tr><tr><td><input checked="" type="checkbox"/></td><td>2</td><td>20040020518</td><td>2004-05-02</td><td>DeYoung et al.</td><td>A1</td><td></td><td></td></tr></tbody></table><div>Signature  9/23/05</div><table border="1"><tr><td>Examiner Name</td><td>Date</td></tr></table></div></div>								init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass	<input checked="" type="checkbox"/>	1	5186594	1993-02-16	Toshima et al.				<input type="checkbox"/>	2	5769588	1998-06-23	Toshima et al.				<input type="checkbox"/>	3	5906866	1999-05-25	Webb				<input type="checkbox"/>	4	5975492	1999-11-02	Brenes				<input type="checkbox"/>	5	6122566	2000-09-19	Nguyen et al.				<input type="checkbox"/>	6	6355072	2002-03-12	Racette et al.	B1			<input checked="" type="checkbox"/>	7	6454519	2002-09-24	Toshima et al.	B1			init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass	<input checked="" type="checkbox"/>	1	20030205510	2003-11-06	Jackson	A1			<input checked="" type="checkbox"/>	2	20040020518	2004-05-02	DeYoung et al.	A1			Examiner Name	Date
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FORM PTO-1449 (Modified)				U.S. Department of Commerce Patent and Trademark Office		Attorney Docket No.: SSI-04001		Serial No.: 10/680,783	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT <small>(Use Several Sheets If Necessary)</small>						Applicants: William D. Jones			
(37 CFR § 1.98(b))						Filing Date: October 6, 2003		Group Art Unit: 1765	

U.S. PATENT DOCUMENTS							
Examiner Initials	Serial / Patent Number	Issue Date	Applicant / Patentee	Class	Subclass	Filing Date	
	AA						
	AB						
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	AO						
	AP						

FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS								
		Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation	
							Yes	No
1W	AQ	JP 8-206485	08/13/96	JP	B01J	3/06		X
	AR							
	AS							

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)	
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	AV
	AW
	AX
	AY
	AZ

Examiner: <u>1W 4</u>	Date Considered: <u>8/23/05</u>
EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8
 Stylesheet Version v1.8.0

Title of
 Invention **HIGH-PRESSURE CHAMBER FOR A SEMICONDUCTOR WAFER**

Application Number: 10/680783

10/680783

Confirmation Number: 5859

First Named Applicant: William Jones

Attorney Docket Number:

Search string: (5186594 or 5769588 or 5906866 or 5975492 or 6122566 or 6355072 or 6454519 or 20030205510 or 20040020518).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents.

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	1	5186594	1993-02-16	Toshima et al.			
	2	5769588	1998-06-23	Toshima et al.			
	3	5906866	1999-05-25	Webb			
	4	5975492	1999-11-02	Brenes			
	5	6122566	2000-08-19	Nguyen et al.			
	6	6355072	2002-03-12	Racette et al.	BI		
	7	6454519	2002-09-24	Toshima et al.	BI		

US Published Applications

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	1	20030205510	2003-11-06	Jackson	A1		
	2	20040020518	2004-05-02	DeYoung et al.	A1		

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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**Title of
Invention**

HIGH-PRESSURE PROCESSING CHAMBER FOR A
SEMICONDUCTOR WAFER

Application Number : 10/680783
Confirmation Number: 5859
First Named Applicant: William Jones
Attorney Docket Number:



Art Unit:

Examiner:

Search string: (3623627 or 4426358 or 4574184 or 5374829 or 5474410 or 5879459 or 6048494
or 6062853 or 6089377 or 6406782 or 20010050096).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
<i>WJ</i>	1	3623627	1969-08-22	Alan S. Bolton			
<i>WJ</i>	2	4426358	1984-01-17	Johansson			
<i>WJ</i>	3	4574184	1986-03-04	Wolf et al.			
<i>WJ</i>	4	5374829	1994-12-20	Sakamoto et al.			
<i>WJ</i>	5	5474410	1995-12-12	Ozawa et al.			
<i>WJ</i>	6	5879459	1999-03-09	Gadgil et al.			
<i>WJ</i>	7	6048494	2000-04-11	Annapragada			
<i>WJ</i>	8	6062853	2000-05-16	Shimazu et al.			
<i>WJ</i>	9	6089377	2000-07-18	Shimazu			
<i>WJ</i>	10	6406782	2000-06-18	Johnson et al.	B2		

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

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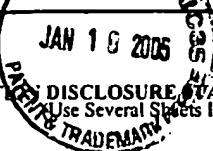
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WJ

9/23/05

Examiner Name

Date

FORM PTO-1449 (Modified)				U.S. Department of Commerce Patent and Trademark Office		Attorney Docket No.: SSI-04001		Serial No.: 10/680,783	
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(37 CFR § 1.98(b))						Filing Date: October 6, 2003		Group Art Unit: 1765	
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	AJ								
FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS									
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							Yes	No	
<i>AK</i>	AK	JP 40 5283511 A	10/29/93	JP	H01L	21/68	X		
<i>AL</i>	AL	JP 2001-77074	03/23/01	JP	H01L	21/304	X		
	AM								
	AN								
	AO								
OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)									
	AP								
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Examiner: <i>h m n l l</i>					Date Considered: <i>9/23/05</i>				
EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.									

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Electronic Version v1.8

Stylesheet Version v1.8.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER		
Application Number:	10/600783	*10/680783*	
Confirmation Number:	5859		
First Named Applicant:	William Jones		
Attorney Docket Number:			
Search string:	(3623627 or 4426358 or 4574184 or 5374829 or 5474410 or 5879459 or 6048494 or 6062853 or 6089377 or 6406782 or 20010050096).pn.		
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1	3623627	1969-08-22	Alan S. Bolton
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			B2
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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**Title of
Invention****HIGH-PRESSURE PROCESSING CHAMBER FOR A
SEMICONDUCTOR WAFER**

Application Number : 10/680783
 Confirmation Number: 5859
 First Named Applicant: William Jones



Attorney Docket Number:

Art Unit:

Examiner:

Search string: (3681171 or 4827867 or 5009738 or 6221781 or 6306564 or 6497239 or
 20030005948).pn

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US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
1	1	3681171	1972-08-01	Toku Hojo et al.			
2	2	4827867	1989-05-09	Takei et al.			
3	3	5009738	1991-04-23	Gruenwald et al.			
4	4	6221781	2001-04-24	Siefering et al.	B1		
5	5	6306564	2001-10-23	Mullee	B1		
6	6	6497239	2002-12-24	Farmer et al.	B2		

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
1	1	20030005948	2003-01-09	Matsuno et al.	A1		

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 9/23/05

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER						
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Application Number : 10/680783

Confirmation Number: 5859


First Named Applicant: William Jones

Attorney Docket Number:

Art Unit:

Examiner:

Search string: (3689025 or 5679169 or 6021791 or 6109296 or 6465403 or 6508259 or 6509141 or 6635565 or 6641678).pn



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US Patent Documents

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init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
AK	1	3689025	1972-09-05	Kiser			
	2	5679169	1997-10-21	Gonzales et al.			
	3	6021791	2000-02-08	Dryer et al.			
	4	6109296	2000-08-29	Austin			
	5	6465403	2002-10-15	Skee	B1		
	6	6508259	2003-01-21	Tseronis et al.	B1		
	7	6509141	2003-01-21	Mullee	B2		
	8	6635565	2003-10-21	Wu et al.	B2		
AK	9	6641678	2003-11-04	DeYoung et al.	B2		

Signature


Examiner Name	Date
AK	9/23/05

4/8/05

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<i>AK</i>	9/23/05																																		

5/16/05

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Stylesheet Version v18.0

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SEMICONDUCTOR WAFER**

Application Number : 10/680783
 Confirmation Number: 5859
 First Named Applicant: William Jones



Attorney Docket Number:

Art Unit:

Examiner:

Search string: (20030036023 or 20040134515).pn

Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:

That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
9/2	1	20030036023	2003-02-20	Moreau et al.	A1		
1/16	2	20040134515	2004-07-15	Castrucci	A1		

Signature

Examiner Name

Date

A. L.

9/23/05

5/26/05

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER
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Application Number : 10/680783
 Confirmation Number: 5859
 First Named Applicant: William Jones
 Attorney Docket Number:
 Art Unit:
 Examiner:
 Search string: (5494526 or 6333268).pn



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US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
NY	1	5494526	1996-02-27	Paranjpe			
NY	2	6333268	2001-12-25	Starov et al.	B1		

Signature

Examiner Name	Date
1 W H	9/23/05

7/19/05

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER						
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Application Number : 10/680783

Confirmation Number: 5859

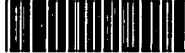
First Named Applicant: William Jones

Attorney Docket Number:

Art Unit:

Examiner:

Search string: (5306350 or 5772783 or 5850747 or 5858107 or 5943721 or 5946945 or 5970554 or 6070440 or 6264753 or 6612317 or 6736149 or 6764552 or 6805801 or 6851148 or 6874513).pn



Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:

That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
✓	1	5306350	1994-04-26	Hoy et al.			
	2	5772783	1998-06-30	Stucker			
	3	5850747	1998-12-22	Roberts et al.			
	4	5858107	1999-01-12	Chao et al.			
	5	5943721	1999-08-31	Lerette et al.			
	6	5946945	1999-09-07	Kegler et al.			
	7	5970554	1999-10-26	Shore et al.			
	8	6070440	2000-06-06	Malchow et al.			
	9	6264753	2001-07-24	Chao et al.			
	10	6612317	2003-09-02	Costantini et al.			
	11	6736149	2004-05-18	Biberger et al.	B2		
	12	6764552	2004-07-20	Joyce et al.	B1		
	13	6805801	2004-10-19	Humayun et al.	B1		
✓	14	6851148	2005-02-08	Preston et al.	B2		

QNT	15	6874513	2005-04-05	Yamagata et al.	B2		
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Signature

Examiner Name	Date

1n L1


9/23/05

8/17/05

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER						
Application Number :		10/680783					
Confirmation Number:		5859					
First Named Applicant:		William Jones					
Attorney Docket Number:							
Art Unit:							
Examiner:							
Search string:		(20030051741).pn					
<p>Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p> <p>That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.</p>							
US Published Applications							
Note: Applicant is not required to submit a paper copy of cited US Published Applications							
init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
1	1	20030051741	2003-03-20	DeSimone et al.			
Signature							
Examiner Name				Date			
[Signature]				9/23/05			